

Title (en)

PATTERNED MATERIALS AND FILMS AND SYSTEMS AND METHODS FOR MAKING THE SAME

Title (de)

GEMUSTERTE MATERIALIEN SOWIE FILME UND SYSTEME UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)

MATÉRIAUX ET FILMS À MOTIFS ET SYSTÈMES ET PROCÉDÉS POUR LES RÉALISER

Publication

**EP 3841434 A4 20211020 (EN)**

Application

**EP 19852650 A 20190820**

Priority

- US 201862720840 P 20180821
- US 2019047273 W 20190820

Abstract (en)

[origin: WO2020041320A1] Disclosed are exemplary embodiments of patterned materials and films (e.g., multilayer films, homogeneous or single layer films, etc.). The films and patterned materials may have controlled and/or tailored performance (e.g., thermal management, electromagnetic interference (EMI) mitigation, electrical conductivity, thermal conductivity, EMI absorbing, magnetic, dielectric, and/or structural performance, etc.). Also disclosed are exemplary embodiments of systems and methods for making such patterned materials and films. In exemplary embodiments, a thermal management and/or electromagnetic interference (EMI) mitigation material comprises a filled dielectric including a pattern of one or more structures protruding outwardly along at least one side of the filled dielectric.

IPC 8 full level

**G03F 7/20** (2006.01); **H01L 21/027** (2006.01); **H01L 21/324** (2006.01); **H01L 21/67** (2006.01); **H01L 51/00** (2006.01); **H05K 9/00** (2006.01)

CPC (source: EP KR)

**B33Y 10/00** (2014.12 - EP); **B33Y 80/00** (2014.12 - EP); **G03F 7/0002** (2013.01 - EP); **G03F 7/0037** (2013.01 - EP); **G03F 7/2012** (2013.01 - KR); **G03F 7/203** (2013.01 - KR); **G03F 7/7095** (2013.01 - KR); **H01L 21/027** (2013.01 - KR); **H01L 21/324** (2013.01 - KR); **H01L 21/67098** (2013.01 - KR); **H01L 23/3737** (2013.01 - EP); **H01L 23/552** (2013.01 - EP); **H05K 7/20472** (2013.01 - EP); **H05K 9/0031** (2022.08 - EP); **H05K 9/0032** (2013.01 - EP); **H05K 9/0083** (2013.01 - EP); **H05K 9/0088** (2013.01 - EP); **H10K 85/151** (2023.02 - KR); **H01L 2224/16227** (2013.01 - EP)

Citation (search report)

- [X1] US 2005001780 A1 20050106 - AISENBREY THOMAS [US]
- [X1] JP 2017171773 A 20170928 - JSP CORP, et al
- [X1] US 2004084196 A1 20040506 - HOGBERG MATS [SE], et al
- See also references of WO 2020041320A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2020041320 A1 20200227**; CN 112585541 A 20210330; DE 202019005902 U1 20230411; EP 3841434 A1 20210630; EP 3841434 A4 20211020; EP 4350442 A2 20240410; EP 4350442 A3 20240703; JP 2021536126 A 20211223; JP 3243042 U 20230731; KR 102661722 B1 20240426; KR 20210033059 A 20210325

DOCDB simple family (application)

**US 2019047273 W 20190820**; CN 201980054705 A 20190820; DE 202019005902 U 20190820; EP 19852650 A 20190820; EP 24158538 A 20190820; JP 2021509837 A 20190820; JP 2023001825 U 20230529; KR 20217007508 A 20190820